1. MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.

2. FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
100 TO 300 MICROINCHES (2.5um - 7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
(40 TO 80 MICROINCHES (1um - 2um) THICK).
BODY SURFACE FINISH: VDI 21–24 (1.12–1.6 Ra).

3. PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX.
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO–220.